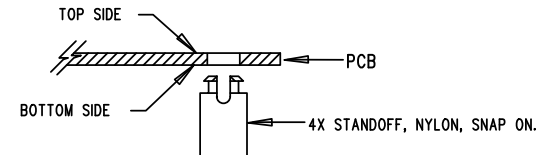




REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	KAUNG H.	2-23-16

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
6. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:




7. INSTALL D4 AS SHOWN BELOW:



8. MARK EACH ASSEMBLY TYPE, OUTPUT VOLTAGE AND CURRENT IN THE WHITE BLOCK AREAS WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY TYPE	VOLTAGE	CURRENT
-A	12V	3A
-B		
-C		
-D		
-E		
-F		

APPROVALS		 LINEAR TECHNOLOGY	1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY	
PCB DES.	KAUNG H.			
APP ENG.	KAUNG H.		TITLE: TOP ASSEMBLY DRAWING HIGH EFFICIENCY IEEE 802.3bt PD WITH PoE IDEAL DIODE BRIDGE	
		SIZE N/A	IC NO. LT4295IUF DEMO CIRCUIT 2475A	REV. 2
SCALE = NONE		FILENAME: DC2475A-1.PCB		SHT 1 OF 2